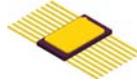


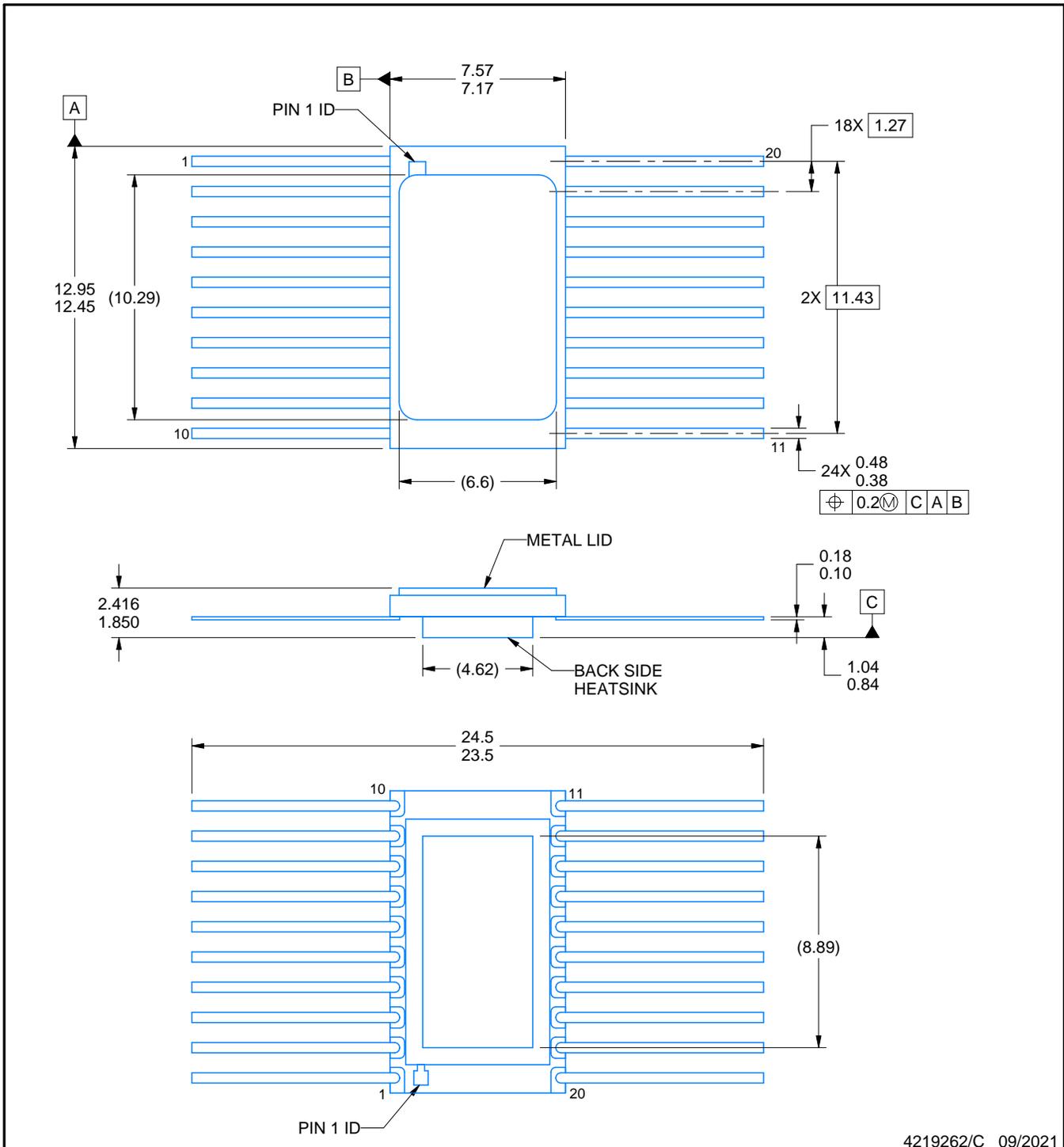
HKH0020A



PACKAGE OUTLINE

CFP - 2.416 mm max height

CERAMIC DUAL FLATPACK



4219262/C 09/2021

NOTES:

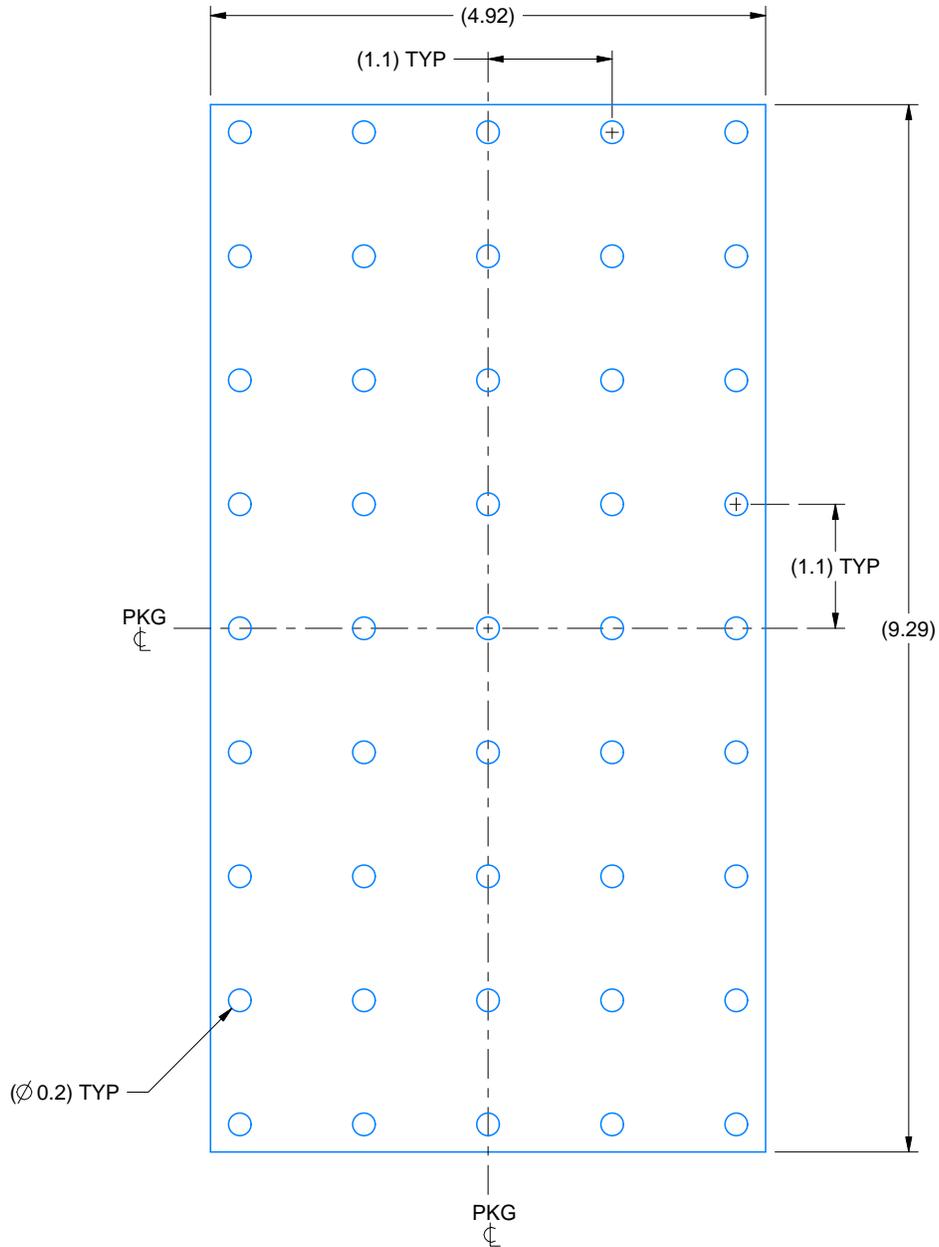
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This package is hermetically sealed with a metal lid.
4. The terminals are gold plated.

EXAMPLE BOARD LAYOUT

HKH0020A

CFP - 2.416 mm max height

CERAMIC DUAL FLATPACK



HEATSINK LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:15X

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